



NASA Electronic Parts and Packaging (NEPP) Program  
**Reliability Evaluation of Ultra Fine  
Conductors and Contacts**



**Task Manager: Dr. Udo Lieneweg (JPL)**

## **Objective**

- To assess the readiness of a microelectronics process in development to achieve minimum linewidths of a quarter micrometer or less while maintaining reliable interconnect properties.
- Benefit power-limited space flight projects
- Provide reliability data to SOAC program

## **Deliverables**

- Electromigration test results
- Thermo-mechanical analysis report [GSFC]
- ESEM/AFM analysis report
- Qualification methodology and design rule generation report

## **Participating Centers**

- Ashok Shama (GSFC)